Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support Distribute - RoHS and IEC 62474 DB Contact Info: Form/Declaration Type: 05/31/2022 Created on:

Details for "LM2575SX-5.0/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LM25755X-5.0/NOPB	SN	Level-3-245C-168 HR	Texas Instruments Electronics	KTT 5	10.2 x 9 x 4.5	1603.8

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Exempt-7(a)	Affected	Yes	Affected

Component Information

			Homogeneous Material Level		Component Level		
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Aluminum and Its Alloys	Aluminum	7429-90-5	0.000001	0.00019	2	0	0
Copper and Its Alloys	Copper	7440-50-8	0.525212	99.997334	999973	0.032748	327
Copper and Its Alloys	Iron	7439-89-6	0.000002	0.000381	4	0	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000002	0.000381	4	0	0
Precious Metals	Silver	7440-22-4	0.000009	0.001714	17	0.000001	0
Sub-Total			0.525226	100	1000000	0.032749	327
Die Attach Adhesive							-
Other Nonferrous Metals and Alloys	Lead	7439-92-1	5.161611	95.499987	955000	0.321834	3218
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.108097	2.00008	20000	0.00674	67
Precious Metals	Silver	7440-22-4	0.135121	2.500005	25000	0.008425	84
Sub-Total			5.404829	100	1000000	0.336999	3370
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	794.947566	99.60004	996000	49.566083	495661
Copper and Its Alloys	Phosphorus	7723-14-0	0.079806	0.009999	100	0.004976	50
Other Nonferrous Metals and Alloys	Tin	7440-31-5	1.19709	0.149985	1500	0.07464	746
Precious Metals	Silver	7440-22-4	1.915344	0.239976	2400	0.119424	1194
Sub-Total			798.139806	100	1000000	49.765123	497651
Lead Frame Plating							-
Other Nonferrous Metals and Alloys	Tin	7440-31-5	6.86	100	1000000	0.427731	4277
Sub-Total			6.86	100	1000000	0.427731	4277
Mold Compound							-
Other Inorganic Materials	Fused Silica	60676-86-0	699.042894	89	890000	43.586293	435863
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	23.563244	3	30000	1.469201	14692
Thermoplastics	Epoxy	85954-11-6	62.835316	8	80000	3.917869	39179
Sub-Total			785.441454	100	1000000	48.973363	489734
Semiconductor Device	·	·					
Ceramics / Glass	Doped Silicon	7440-21-3	7.442267	100	1000000	0.464036	4640
Sub-Total			7.442267	100	1000000	0.464036	4640
Total			1603.813582			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component See Glossary of Terms for more details.

Important Part Information

There is a remove possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology For an explanation of the methods used to determine material weights, See Product Content Methodolo

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database

Important Information/Disclaimer

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Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/31/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (5b203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.